

STUD BUMPING APPARATUS

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ABSTRACT

The invention provides an apparatus and a method for forming conductive bumps on a plurality of semiconductor devices with an oxidizable material. The apparatus comprises a bump forming device, a chamber system adapted to house the semiconductor devices and a gas supply for supplying an inert gas into the chamber system. A support table is provided for supporting the semiconductor devices during bumping, and the said support table is operative to move the semiconductor devices from a bumping site into the chamber system after bumping.

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(Figure 3)